Device Material Content

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Package: 400 caBGA
Total Device Weight 743.47 **Milligrams**

Package Code: BG400
Products: LIFCL

Assembly: ASEK
Size (mm): 17 x 17 x 0.7
Lead pitch (mm): 0.8
MSL: 3
Reflow max (ºC): 260

	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.59%	11.796	1.59%	11.796	Silicon chip	7440-21-3	100.00%	Die size: 4.805 x 5.185mm
Mold Compound	53.84%	400.272	47.11%	350.238	Silica	60676-86-0	87.50%	Mold Compound: Kyocera KE-G1250AAS
			3.50%	26.018	Epoxy resin	-	6.50%	
			2.96%	22.015	Phenol Resin	-	5.50%	
			0.27%	2.001	Carbon Black	1333-86-4	0.50%	
D/A Epoxy	0.57%	4.247	0.46%	3.398	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel (Ablebond) 2100A
			0.11%	0.849	Esters & resins	-	20.00%	
Wire	0.35%	2.635	0.35%	2.595	Copper	7440-50-8	98.50%	0.8 mil diameter; 1 wire per solder ball
			0.01%	0.040	Palladium	7440-05-3	1.50%	
			0.00%	0.000	Gold	7440-57-5		
Solder Balls	20.63%	153.376	19.91%	148.007	Tin (Sn)	7440-31-5	96.50%	SAC305
			0.62%	4.601	Silver (Ag)	7440-22-4	3.00%	
			0.10%	0.767	Copper (Cu)	7440-50-8	0.50%	
Substrate	5.98%	44.489	1.91%	14.237	BT Resins	-	32.00%	BT Resin CCL-HL832NX-A
			4.07%	30.253	Glass fiber	65997-17-3	68.00%	
Foil	1.61%	11.977	1.61%	11.977	Copper	7440-50-8	100.00%	
Solder Mask	15.42%	114.673	8.39%	62.348	Quartz	14808-60-7	54.37%	Solder mask PSR4000 AUS 308
			1.13%	8.406	Dipropylene glycol monomethyl ether	34590-94-8	7.33%	
			0.51%	3.807	Morpholine derivative	71868-10-5	3.32%	
			0.46%	3.440	Silicon dioxide	7631-86-9	3.00%	
			0.46%	3.440	Silica, amorphous	112945-52-5	3.00%	
			0.04%	0.275	Carbon black	1333-86-4	0.24%	
			4.43%	32.957	Trade secret ingredients	-	28.74%	

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